



Material Content Data Sheet



Sales Product Name		BFP 640FESD H6327		Issued		20. July 2018		
MA#		MA000908278						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1457	
	inorganic material	silicon	7440-21-3	0.024	1.27	1.46	12700	14533
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.25	39.42	392471	394127
wire	noble metal	gold	7440-57-5	0.007	0.39	0.39	3883	3883
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5132	
	plastics	epoxy resin	-	0.206	11.03		110332	
	inorganic material	silicondioxide	60676-86-0	0.744	39.76	51.30	397707	513171
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26163	26163
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48123	48123
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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